



# NEWAY SINOPHC TECH. LIMITED

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## Certificate of Analysis

**Product Name: Photoresist (Positive/Negative Type)**

### Product Information

Product Number PR-20260228  
Batch Number PR-SH2026022801  
Brand SIGALD  
CAS Number N/A (Complex photoresist mixture)  
MDL Number N/A (No specific MDL for composite photoresist)  
Formula Blend of Photoresist Resin, Photoinitiator, Organic Solvent & Additives  
Formula Weight Variable (Polymer mixture)  
Quality Release Date 28 FEB 2026

### Test Results

Test	Specification (Semiconductor & Lithography Industry Standard)	Result	Unit	Test Method
Appearance (Color)	Colorless to pale yellow	Colorless	-	Visual Inspection
Appearance (Form)	Transparent homogeneous liquid	Transparent liquid	-	Visual Inspection
Solid Content	20.0-25.0%	22.5%	%	Gravimetric Method (105°C, 3h)
Lithography Resolution	≤ 5.0 μm	3.0 μm	μm	Optical Lithography Test
Developing Speed (23°C)	30-60 s	42 s	s	Standard Developer Immersion Test
Viscosity (25°C)	20-50 mPa·s	35.2 mPa·s	mPa·s	Rotational Viscometry
Flash Point	≥ 60°C	68°C	°C	Closed Cup Flash Point Tester
Heavy Metals (Pb)	≤ 5 ppm	0.8 ppm	ppm	Atomic Absorption Spectrometry (AAS)
Heavy Metals (As)	≤ 1 ppm	0.2 ppm	ppm	Atomic Fluorescence Spectrometry (AFS)
Particle Size (≥1 μm)	≤ 10 pcs/mL	3 pcs/mL	pcs/mL	Liquid Particle Counter
Substrate Adhesion	Grade 0 (no peeling)	Grade 0	-	Cross-Cut Adhesion Test
Supplier Information	Confirmed	Confirmed	-	-
Registered Trademark	Confirmed	Confirmed	-	-

### Certification

This batch of product has been tested in accordance with semiconductor and lithography industry standards for photoresist and meets all specified requirements. It is qualified for use.  
Issue Date:28 FEB 2026